



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-09-26
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HTDZ*EBU4360	A	SH1A	2014-09-26
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.000	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10X9.1X4.5	2	Through-hole	
Comment	Package: TO 220 AB NON ISOL; MD valid for FERD20M60ST			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HTD2*EBU4360					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	10.521	mg	supplier	die	Silicon (Si)	7440-21-3		10.303	mg	979280	5423
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.072	mg	6843	38
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.014	mg	1331	7
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.045	mg	4277	24
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.005	mg	475	3
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.062	mg	5893	33
die (s)				supplier	back side metallization	Vanadium (V)	7440-62-2		0.005	mg	475	3
die (s)				supplier	back side metallization	Silver (Ag)	7440-22-4		0.015	mg	1426	8
Leadframe	Copper & its alloys	1141.614	mg	supplier	alloy	Copper (Cu)	7440-50-8		1140.116	mg	998688	600061
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.525	mg	460	276
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.959	mg	840	505
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.013	mg	11	7
Leadframe				supplier	metallization	Iron Phosphide (Fe2P)	1310-43-6		0.001	mg	1	1
Soft solder	Other Organic Materials	7.471	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	7.135	mg	955026	3755
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.187	mg	25030	98
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.149	mg	19944	78
Bonding wire	Other inorganic materials	3.125	mg	supplier	wire	Aluminium (Al)	7429-90-5		3.124	mg	999680	1644
Bonding wire				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	320	1
encapsulation	Other Organic Materials	733.028	mg	supplier	mold compound	Silica, vitreous	60676-86-0		637.734	mg	870000	335649
encapsulation				supplier	mold compound	Epoxy resin	Proprietary		73.303	mg	100000	38581
encapsulation				supplier	mold compound	Phenol resin	Proprietary		18.326	mg	25000	9645
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		3.665	mg	5000	1929
connections coating	Solder	4.241	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.241	mg	1000000	2232